

### **Absolute Maximum Ratings\*** TA = 25°C unless otherwise noted

Symbol	Parameter	Value	Units	
V <sub>DG</sub>	Drain-Gate Voltage	30	V	
V <sub>GS</sub>	Gate-Source Voltage	- 30	V	
I <sub>GF</sub>	Forward Gate Current	50	mA	
T <sub>J</sub> ,T <sub>stg</sub>	Operating and Storage Junction Temperature Range	-55 to +150	°C	

\*These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

NOTES:

1) These ratings are based on a maximum junction temperature of 150 degrees C.
2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations

### **Thermal Characteristics** TA = 25°C unless otherwise noted

Symbol	Characteristic	Max Ur		Units
		PN4391-4393	*MMBF4391-4393	
PD	Total Device Dissipation	625	350	mW
	Derate above 25°C	5.0	2.8	mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	125		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	556	°C/W

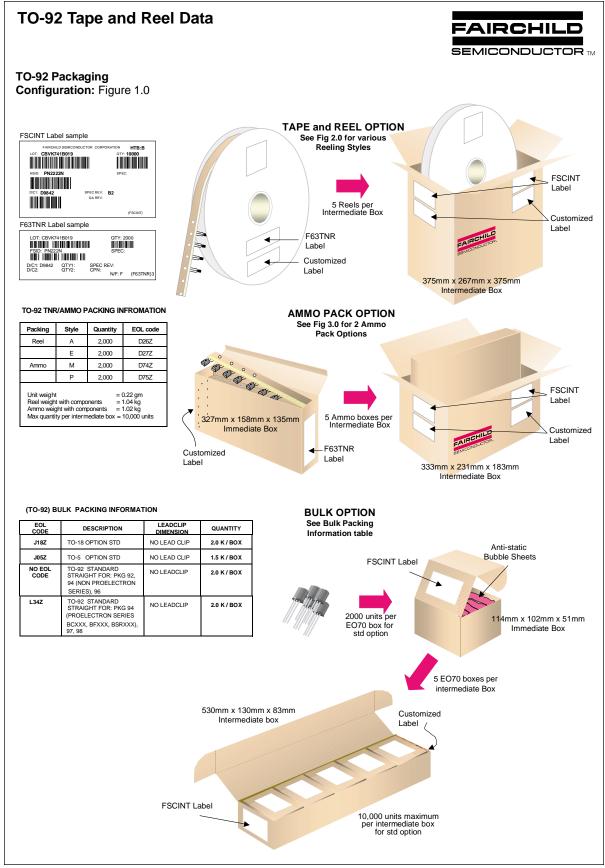
\*Device mounted on FR-4 PCB 1.6" X 1.6" X 0.06."

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# N-Channel Switch (continued)

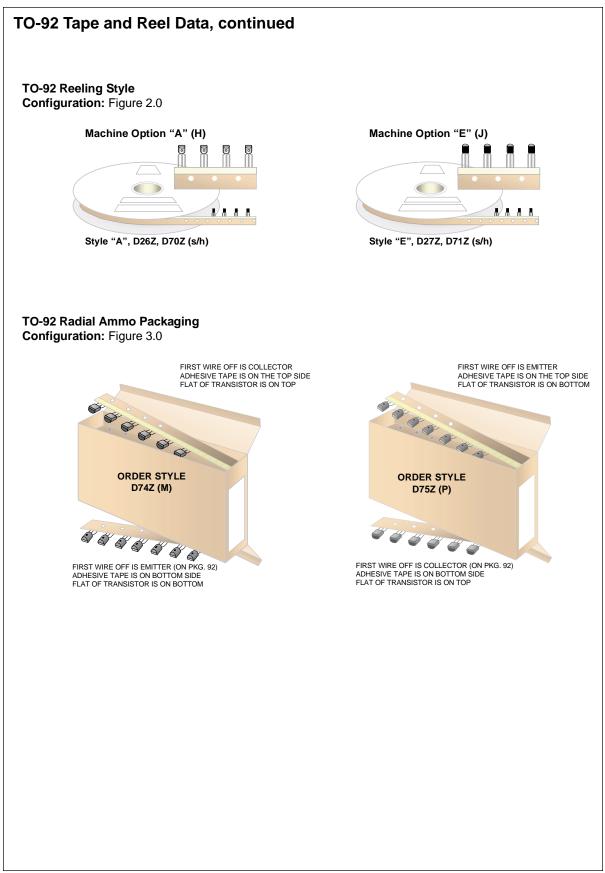
Symbol	Parameter	Test Conditions		Min	Max	Units
OFF CHAF	RACTERISTICS					
V <sub>(BR)GSS</sub>	Gate-Source Breakdown Voltage	$I_{G} = 1.0 \ \mu A, V_{DS} = 0$		- 30		V
I <sub>GSS</sub>	Gate Reverse Current	$V_{GS} = -15 \text{ V}, \text{ V}_{DS} = 0$			- 1.0	nA
		$V_{GS} = -15 V$ , $V_{DS} = 0$ , $T_A =$	150°C		- 0.2	μA
VGS(off)	Gate-Source Cutoff Voltage	$V_{DS} = 20 V, I_D = 1.0 nA$	4391	- 4.0	- 10	V
			4392 4393	- 2.0 - 0.5	- 5.0 - 3.0	V V
V <sub>GS(f)</sub>	Gate-Source Forward Voltage	$I_{G} = 1.0 \text{ mA}, V_{DS} = 0$	1000		1.0	V
I <sub>D(off)</sub>	Drain Cutoff Leakage Current	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = - 12 V	4391		0.1	nA
	_	$V_{DS} = 20 \text{ V}, V_{GS} = -7.0 \text{ V}$	4392		0.1	nA
		$V_{DS} = 20 \text{ V}, V_{GS} = -5.0 \text{ V}$ $V_{DS} = 20 \text{ V}, V_{GS} = -12 \text{ V},$	4393		0.1	nA
		$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = -12 \text{ V},$ $T_A = 150^{\circ}\text{C}$	4391		0.2	μA
		$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = -7.0 \text{ V},$				•
		$T_{A} = 150^{\circ}C$	4392		0.2	μA
		$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = -5.0 \text{ V},$ $T_A = 150^{\circ}\text{C}$	4393		0.2	μA
		TA = 150 C	4333			p
ON CHARA	ACTERISTICS					
IDSS	Zero-Gate Voltage Drain Current*	$V_{DS} = 20 V, V_{GS} = 0$	4391	50	150	mA
			4392 4393	25 5.0	75 30	mA mA
V <sub>DS(on)</sub>	Drain-Source On Voltage	I <sub>D</sub> = 12 mA, V <sub>GS</sub> = 0	4393	0.0	0.4	V
V DS(on)		$I_D = 6.0 \text{ mA}, V_{GS} = 0$	4392		0.4	V
		$I_D = 3.0 \text{ mA}, V_{GS} = 0$	4393		0.4	V
r <sub>DS(on)</sub>	Drain-Source On Resistance	$I_D = 1.0 \text{ mA}, V_{GS} = 0$	4391		30	Ω
			4392 4393		60 100	Ω Ω
			1000			22
SMALL-SI	GNAL CHARACTERISTICS					
r <sub>ds(on)</sub>	Drain-Source On Resistance	$V_{DS} = V_{GS} = 0$ , f= 1.0 kHz	4391		30	Ω
			4392		60 100	Ω
Ciss	Input Capacitance	4393     100       V <sub>DS</sub> = 20, V <sub>GS</sub> = 0, f = 1.0 MHz     14		Ω pF		
	Reverse Transfer Capacitance $V_{GS} = -12 \text{ V}, \text{ f} = 1.0 \text{ MHz}$ <b>4391</b>			3.5	pF	
Orss		$V_{GS} = -7.0 \text{ V}, f = 1.0 \text{ MHz}$	4392		3.5	pF
		V <sub>GS</sub> = - 5.0 V, f = 1.0 MHz	4393		3.5	pF
0.4 <i>4</i> <b>-</b> 0.44						
	NG CHARACTERISTICS	1 10 4	4204		E 0	
tr		$I_{D(on)} = 12 \text{ mA}$ $I_{D(on)} = 6.0 \text{ mA}$	4391 4392		5.0 5.0	ns ns
		$I_{D(on)} = 3.0 \text{ mA}$	4392 4393		5.0	ns
t <sub>f</sub>	Fall Time	$V_{GS(off)} = 12 V$	4391		15	ns
		$V_{GS(off)} = 6.0 V$	4392		20	ns
		$V_{GS(off)} = 3.0 V$	4393		30	ns
t <sub>on</sub>	Turn-On Time	$I_{D(on)} = 12 \text{ mA}$	4391		15	ns
		$I_{D(on)} = 6.0 \text{ mA}$	4392 4393		15 15	ns ns
t_"	Turn-Off Time	$I_{D(on)} = 3.0 \text{ mA}$ $V_{GS(off)} = 12 \text{ V}$	4393 4391		20	ns
t <sub>off</sub>		$V_{GS(off)} = 12 V$ $V_{GS(off)} = 6.0 V$	4391		35	ns
		$V_{GS(off)} = 0.0 V$ $V_{GS(off)} = 3.0 V$	4393		50	ns

# PN4391 / 4392 / 4393 / MMBF4391 / 4392 / 4393

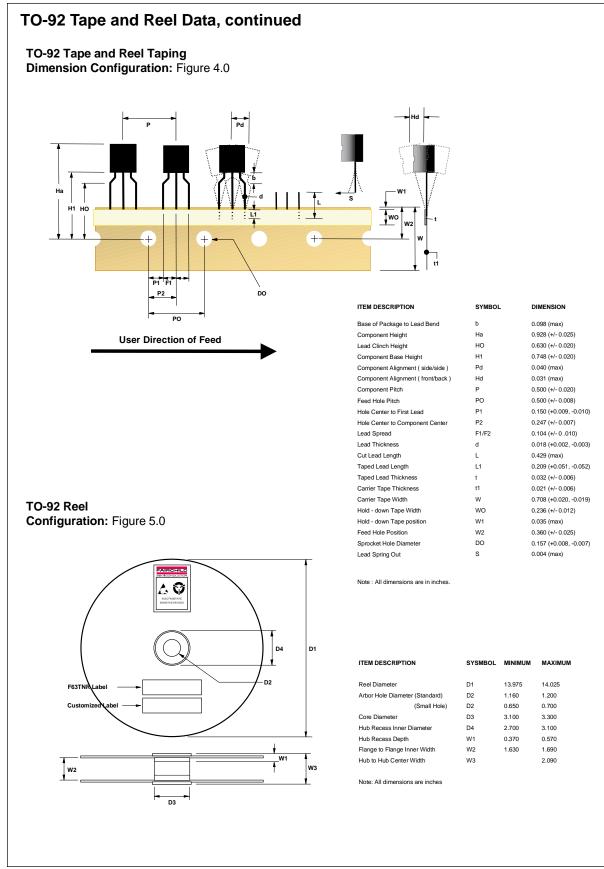


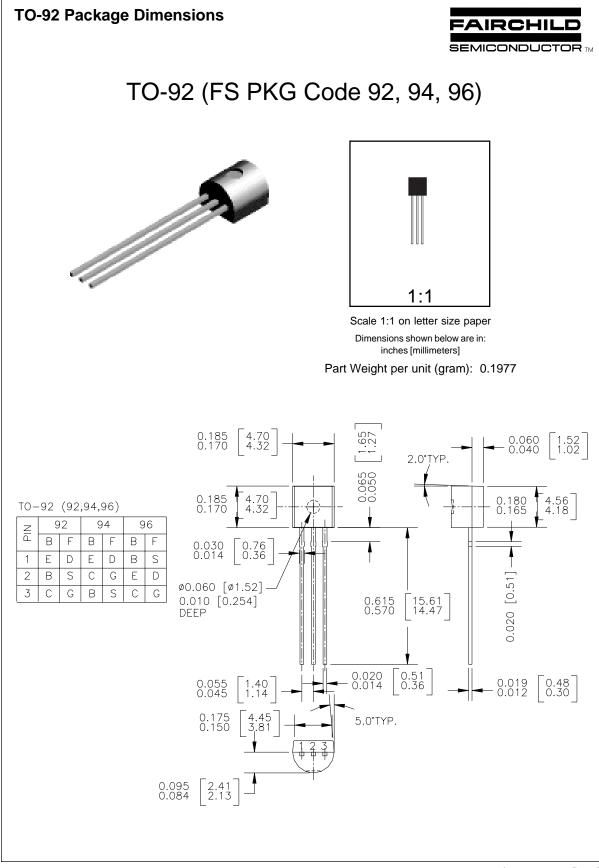
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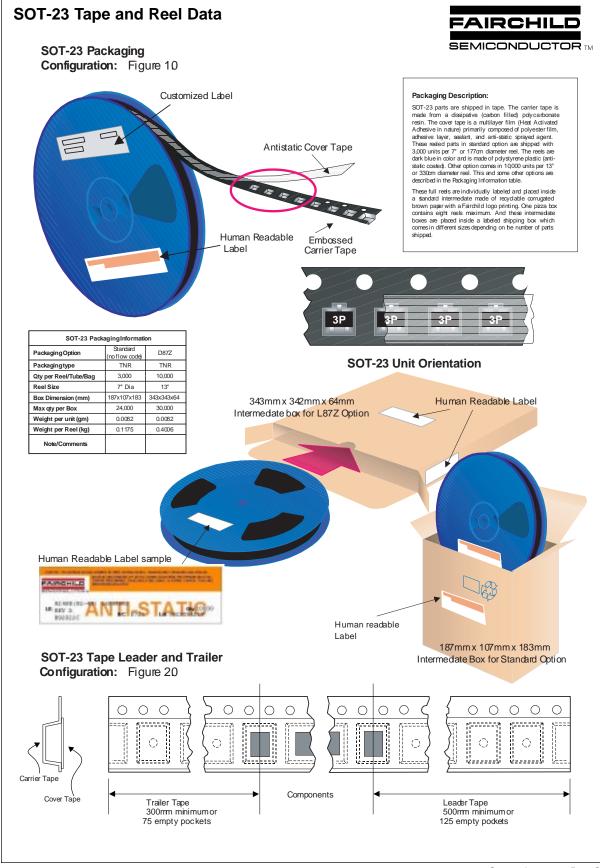
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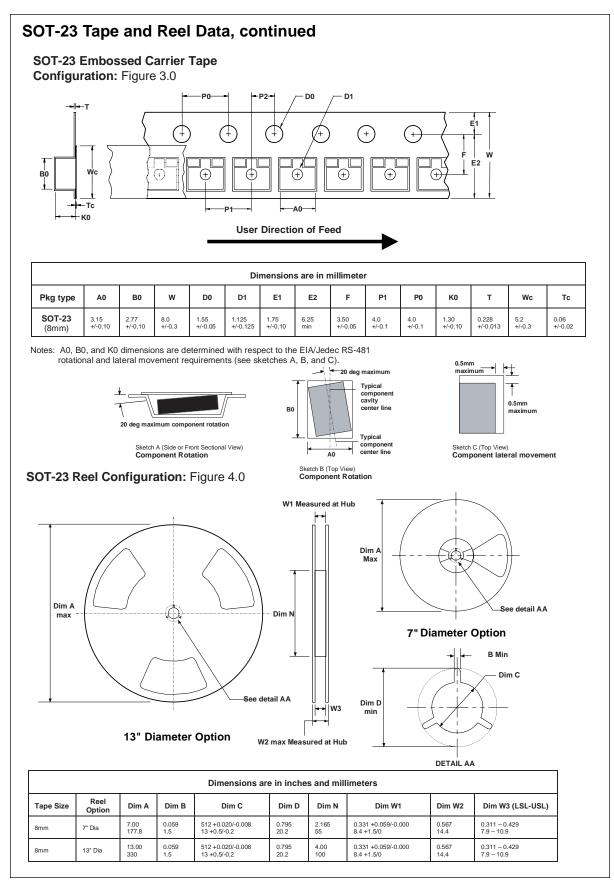
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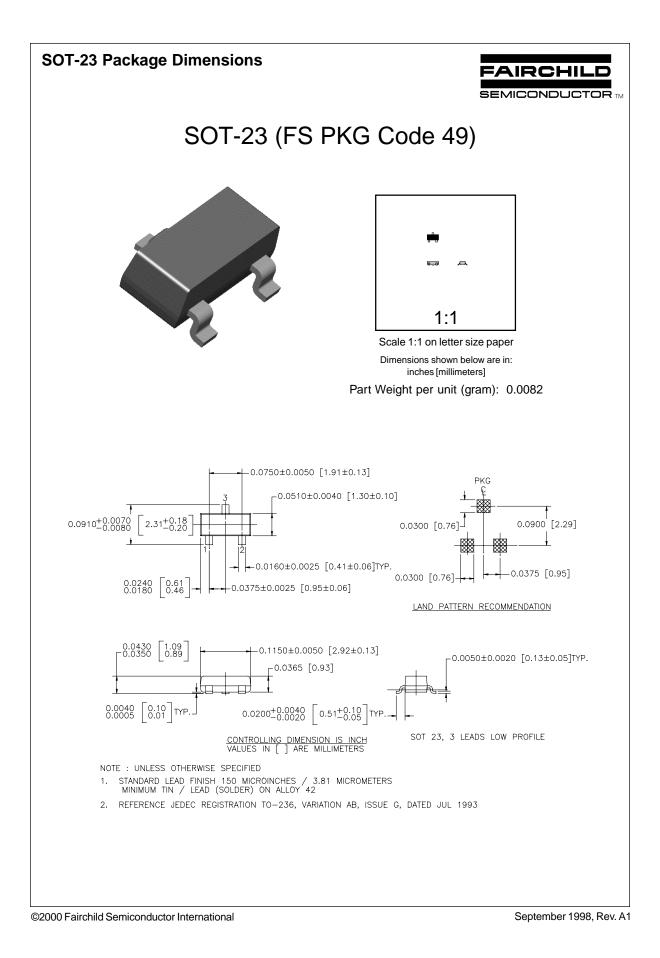


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